



**BSI Standards Publication**

## **Test methods for electrical materials, printed boards and other interconnection structures and assemblies**

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Part 5-601: General test methods for materials and assemblies — Reflow soldering ability test for solder joint, and reflow heat resistance test for printed boards

## National foreword

This British Standard is the UK implementation of EN IEC 61189-5-601:2021. It is identical to IEC 61189-5-601:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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**Compliance with a British Standard cannot confer immunity from legal obligations.**

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### Amendments/corrigenda issued since publication

| Date | Text affected |
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